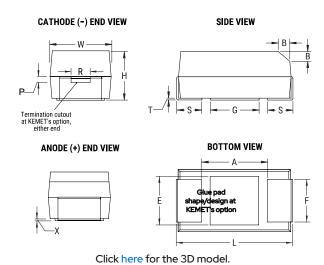# T541X476M035AH6710

Aliases (DLA Drawing 04052-062B)

T541 HRA, Tantalum, Polymer Tantalum, HRA Multi-Anode, 47 uF, 20%, 35 VDC, SMD, Polymer, Molded, High Reliability, Multi-Anode, Low ESR, N/A, 60 mOhms, 7343, 4.3 mm, 1.3 mm

### CATHODE (-) END VIEW

### SIDE VIEW

Termination cutout at KEMET's option, either end

### ANODE (+) END VIEW

### BOTTOM VIEW

Glue pad shape/design at KEMET's option

Click here for the 3D model.

## General Information

| | |
|---|---|
| Series | T541 HRA |
| Dielectric | Polymer Tantalum |
| Style | SMD Chip |
| Description | SMD, Polymer, Molded, High Reliability, Multi-Anode, Low ESR |
| Features | Non-Combustible, Multiple Anode, Low ESR, High Reliability |
| RoHS | No |
| Prop 65 | WARNING: Cancer and reproductive harm – https://www.p65warnings.ca.gov/ . |
| SCIP Number | b064b03e-bd75-42af-b342-1fe94dec2340 |
| Termination | Tin Lead (SnPb) |
| Qualifications | DLA Drawing 04052 |
| AEC-Q200 | No |
| Typical Component Weight | 410.89 mg |
| Shelf Life | 52 Weeks |
| MSL | 3 |

## Dimensions

| | |
|---|---|
| L | 7.3mm +/-0.3mm |
| W | 4.3mm +/-0.3mm |
| H | 4mm +/-0.3mm |
| T | 0.13mm REF |
| S | 1.3mm +/-0.3mm |
| F | 2.4mm +/-0.1mm |
| A | 3.8mm MIN |
| B | 0.5mm +/-0.15mm |
| E | 3.5mm REF |
| G | 3.5mm REF |
| P | 1.7mm REF |
| R | 1mm REF |
| X | 0.1mm +/-0.1mm REF |

## Specifications

| | |
|---|---|
| Capacitance | 47 uF |
| Tolerance | 20% |
| Voltage DC | 35 VDC (105C), 23.45 VDC (125C) |
| Temperature Range | -55/+125°C |
| Rated Temperature | 105°C |
| Life | 2000 Hrs (125C) |
| Humidity | 60C, 90% RH, 500 Hours, rated voltage |
| Dissipation Factor | 10% 120Hz 25C |
| Failure Rate | N/A |
| ESR | 60 mOhms (100kHz 25C) |
| Ripple Current | 2121 mA (rms, 100kHz 45C) |
| Leakage Current | 165 uA (5min 25°C) |
| Testing and Reliability | 10 Cycles Surge Current Testing At -55C +0C/-5C And +85C +/-5C After Voltage Aging |

## Packaging Specifications

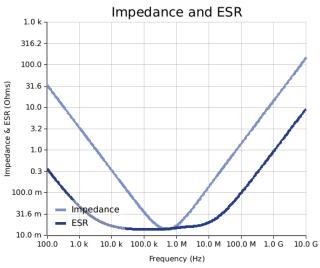| | |
|---|---|
| Packaging | T&R, 178mm |
| Packaging Quantity | 500 |

# T541X476M035AH6710

Aliases (DLA Drawing 04052–062B)

T541 HRA, Tantalum, Polymer Tantalum, HRA Multi–Anode, 47 uF, 20%, 35 VDC, SMD, Polymer, Molded, High Reliability, Multi–Anode, Low ESR, N/A, 60 mOhms, 7343, 4.3 mm, 1.3 mm

## Simulations

For the complete simulation environment please visit K–SIM.



Impedance and ESR



Capacitance and Inductance



Current and Voltage

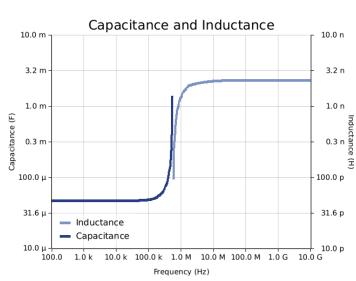

S11



S21

# T541X476M035AH6710
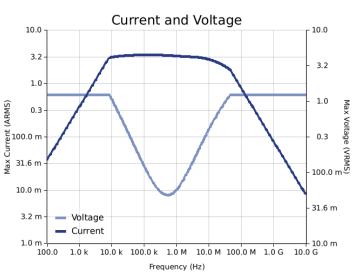
## Aliases (DLA Drawing 04052–062B)

T541 HRA, Tantalum, Polymer Tantalum, HRA Multi–Anode, 47 uF, 20%, 35 VDC, SMD, Polymer, Molded, High Reliability, Multi–Anode, Low ESR, N/A, 60 mOhms, 7343, 4.3 mm, 1.3 mm
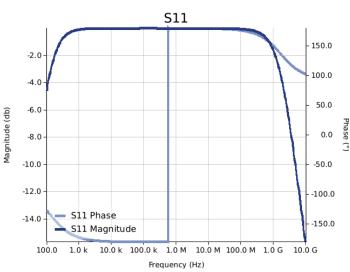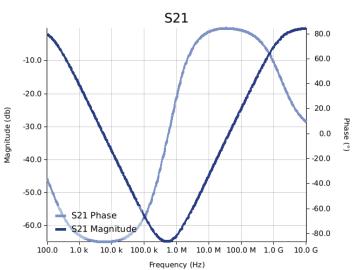
**These are simulations.**
This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.
- The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
- The effects shown herein are based on measured data from a multiple part sample of the parts in question.
- Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
- The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages generated at any other harmonics.
- Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K–SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K–SIM.